

Amendments to the Specification

Please replace paragraph [0043] with the following rewritten paragraph:

[0001] Polysilicon surface micromachining processes, such as the Multi-User Microelectromechanical System (MUMPS) process by Cronos Integrated Microsystems, are also suitable for this invention. The MUMPS process is a standard 3-layer polysilicon surface micromachining process. Another process involving surface micromachining on top of a silicon-on-insulator (SOI) wafer may also be used. This process is described in copending U.S. Patent Application Nos. ~~[Attorney Docket Nos. D/98777, D/98777Q and D/98777Q1]~~09/467,526, 09/468,423 and 09/468,141, incorporated herein by reference in their entirety.